

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Previously Presented) A method of making a microstructure on a circuit board that includes a dielectric layer having a first surface and a second surface opposite to the first surface, and a first conductor layer formed on the first surface of the dielectric layer; the method comprising the steps of:

(A) forming a metal structure on the circuit board, the metal structure extending from the first conductor layer toward the second surface of the dielectric layer, said step A including the sub-steps of

(a) forming a hole unit in the dielectric layer, the hole unit being formed so it extends from the second surface to the first surface, and

(b) filling the hole unit with the metal structure; and

(B) removing at least a portion of the dielectric layer adjacent to the first conductor layer and the metal structure to result in the microstructure having one side defined by the first conductor layer.

2. (Canceled)

3. (Previously Presented) The method of claim 1, wherein the circuit board further includes a second conductor layer formed on the second surface of the dielectric

layer, the sub-step (a) including: (i) patterning the second conductor layer to expose parts of the second surface of the dielectric layer, and (ii) forming the hole unit in the exposed parts of the second surface of the dielectric layer.

4.-7. (Canceled)

8. (Previously Presented) The method of claim 1, wherein the circuit board further includes a photo-resist layer coated on the second surface of the dielectric layer, the sub-step (a) including: (i) patterning the photo-resist layer to expose parts of the second surface of the dielectric layer, and (ii) forming the hole unit in the exposed parts of the second surface of the dielectric layer.

9. (Previously Presented) The method of claim 1, further comprising the step of: disposing a cover member on the second surface of the dielectric layer after step (B).

10-12. (Canceled)

13. (Previously Presented) The method of claim 1, further comprising the step of: forming a lever member on the second surface of the dielectric layer after sub-step (b), the lever member having one end connected to the metal structure in the hole unit.

14. (Canceled)

15. (Previously Presented) The method of claim 1, wherein removal of the dielectric layer in step (B) is conducted through one of laser ablation, etching, precision machining, and pyrolysis.

16. (Canceled)

17. (Canceled)